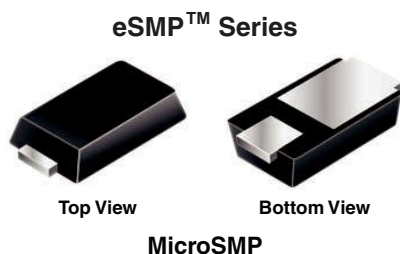




Surface Mount ESD Capability Rectifier



FEATURES

- Very low profile - typical height of 0.65 mm
- Ideal for automated placement
- Oxide planar chip junction
- Low forward voltage drop, low leakage current
- ESD capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



RoHS
COMPLIANT
HALOGEN
FREE

MECHANICAL DATA

Case: MicroSMP

Molding compound meets UL 94 V-0 flammability rating
Base P/N-M3 - halogen-free and RoHS compliant, commercial grade

Base P/NHM3 - halogen-free and RoHS compliant, AEC-Q101 qualified

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test, HM3 suffix meets JESD 201 class 2 whisker test

Polarity: Color band denotes the cathode end

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	1.0 A
V_{RRM}	100 V, 200 V, 400 V, 600 V
I_{FSM}	20 A
V_F at $I_F = 1.0$ A	0.925 V
I_R	1 μ A
T_J max.	175 °C

TYPICAL APPLICATIONS

General purpose, polarity protection, and rail-to-rail protection in both consumer and automotive applications.

MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	MSE1PB	MSE1PD	MSE1PG	MSE1PJ	UNIT
Device marking code		SB	SD	SG	SJ	
Maximum repetitive peak reverse voltage	V_{RRM}	100	200	400	600	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}$	1.0				A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I_{FSM}	20				A
Operating junction and storage temperature range	T_J, T_{STG}	- 55 to + 175				°C

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)

PARAMETER	TEST CONDITIONS	SYMBOL	TYP.	MAX.	UNIT
Maximum instantaneous forward voltage	$I_F = 0.5$ A	$V_F^{(1)}$	0.940	-	V
	$I_F = 1.0$ A		1.016	1.1	
	$I_F = 0.5$ A		0.834	-	
	$I_F = 1.0$ A		0.925	0.98	
Maximum reverse current	Rated V_R	$I_R^{(2)}$	-	1.0	μ A
			3.7	50	
Typical reverse recovery time	$I_F = 0.5$ A, $I_R = 1.0$ A, $I_{rr} = 0.25$ A	t_{rr}	780	-	ns
Typical junction capacitance	4.0 V, 1 MHz	C_J	5	-	pF

Notes

(1) Pulse test: 300 μ s pulse width, 1 % duty cycle

(2) Pulse test: Pulse width \leq 40 ms

MSE1PB thru MSE1PJ

Vishay General Semiconductor



THERMAL CHARACTERISTICS (T _A = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	MSE1PB	MSE1PD	MSE1PG	MSE1PJ	UNIT
Typical thermal resistance	R _{θJA} ⁽¹⁾	110				°C/W
	R _{θJL} ⁽¹⁾	30				
	R _{θJC} ⁽¹⁾	40				

Note

⁽¹⁾ Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 6.0 mm x 6.0 mm copper pad areas. R_{θJL} is measured at the terminal of cathode band.

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS (T _A = 25 °C, unless otherwise noted)					
STANDARD	TEST TYPE	TEST CONDITIONS	SYMBOL	CLASS	VALUE
AEC-Q101-001	Human body model (contact mode)	C = 100 pF, R = 1.5 kW	V _C	H3B	> 8 kV
AEC-Q101-002	Machine model (contact mode)	C = 200 pF, R = 0 W		M4	> 400 V
JESD22-A114	Human body model (contact mode)	C = 150 pF, R = 1.5 kW		3B	> 8 kV
JESD22-A115	Machine model (contact mode)	C = 200 pF, R = 0 W		C	> 400 V
IEC 61000-4-2 ⁽²⁾	Human body model (contact mode)	C = 150 pF, R = 150 W		4	> 8 kV
	Human body model (air-discharge mode) ⁽¹⁾	C = 150 pF, R = 150 W		4	> 15 kV

Notes

⁽¹⁾ Immunity to IEC 61000-4-2 air discharge mode has a typical performance > 30 kV

⁽²⁾ System ESD standard

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
MSE1PJ-M3/89A	0.006	89A	4500	7" diameter plastic tape and reel
MSE1PJHM3/89A ⁽¹⁾	0.006	89A	4500	7" diameter plastic tape and reel

Note

⁽¹⁾ AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)

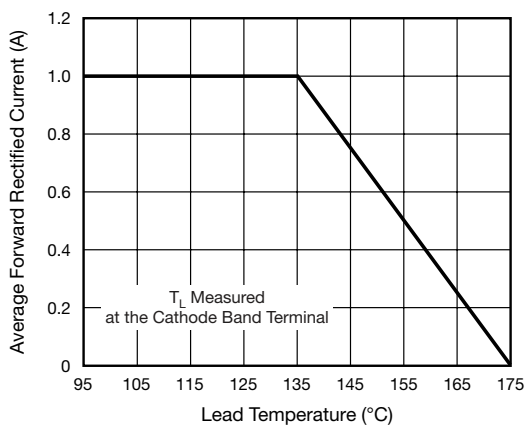


Fig. 1 - Forward Current Derating Curve

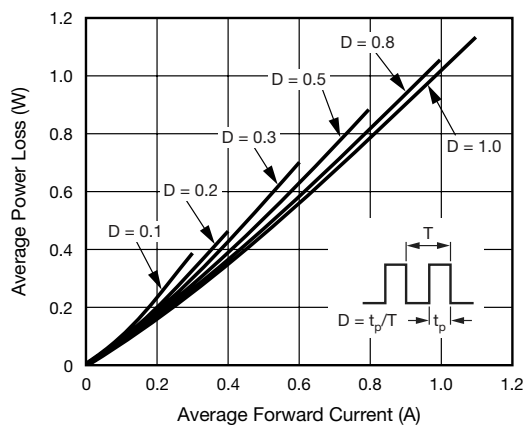


Fig. 2 - Forward Power Loss Characteristics



MSE1PB thru MSE1PJ

Vishay General Semiconductor

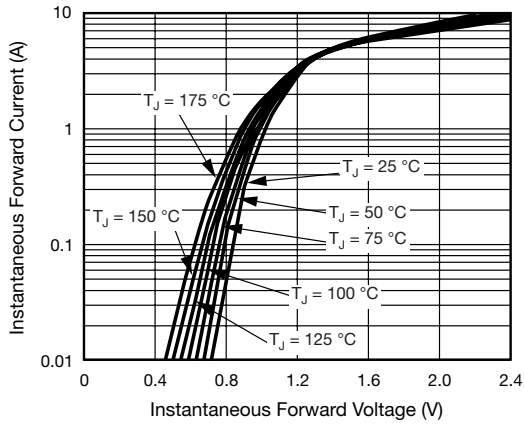


Fig. 3 - Typical Instantaneous Forward Characteristics

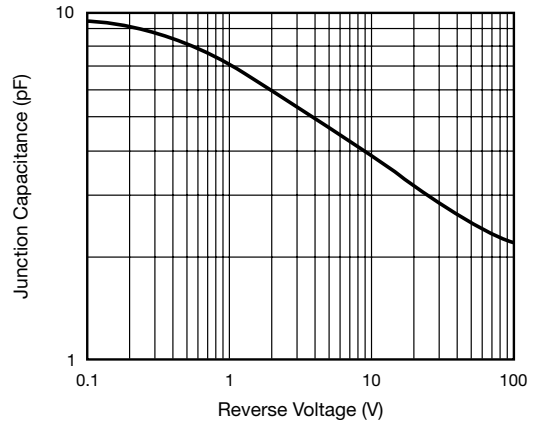


Fig. 5 - Typical Junction Capacitance

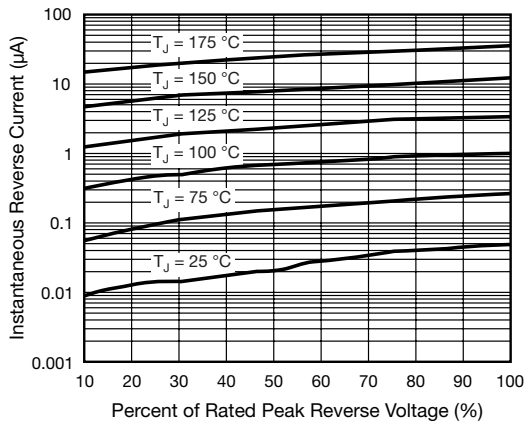


Fig. 4 - Typical Reverse Leakage Characteristics

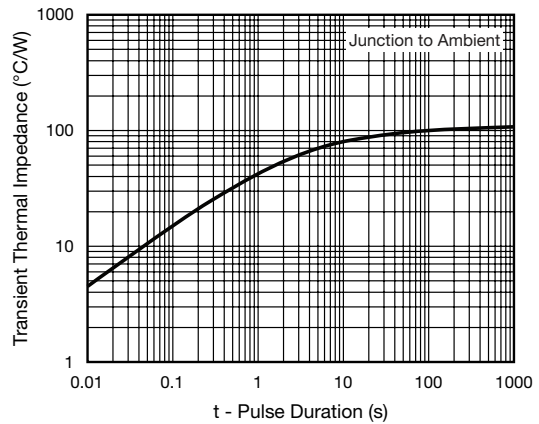
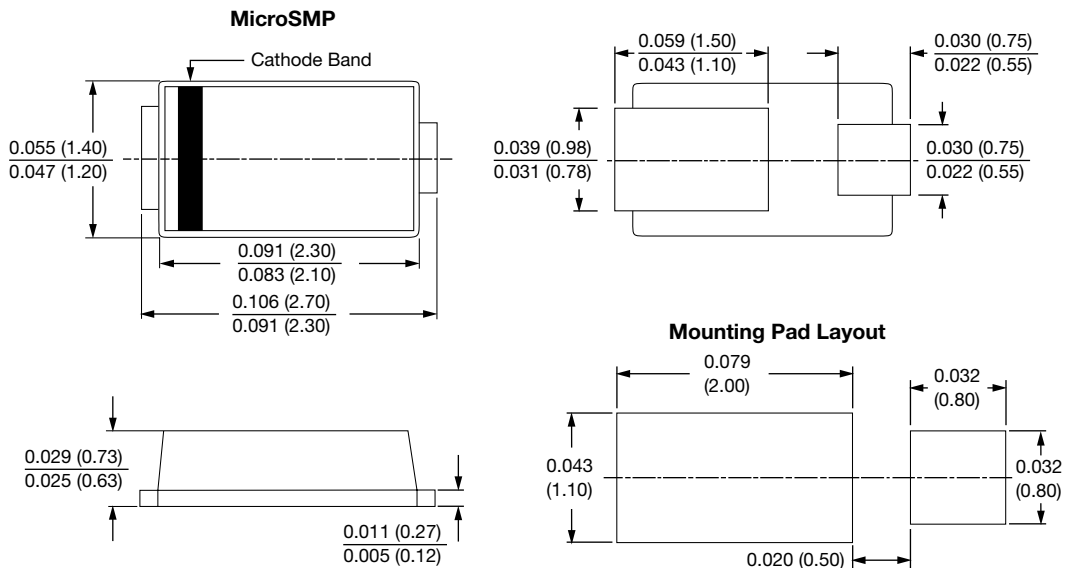


Fig. 6 - Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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